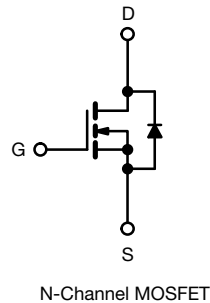


E Series Power MOSFET with Fast Body Diode

Thin-Lead TO-220 FULLPAK


FEATURES

- Fast body diode MOSFET using E series technology
- Reduced t_{rr} , Q_{rr} , and I_{RRM}
- Low figure-of-merit (FOM) $R_{on} \times Q_g$
- Low input capacitance (C_{iss})
- Low switching losses due to reduced Q_{rr}
- Ultra low gate charge (Q_g)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE
Available

APPLICATIONS

- Telecommunications
 - Server and telecom power supplies
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Consumer and computing
 - ATX power supplies
- Industrial
 - Welding
 - Battery chargers
- Renewable energy
 - Solar (PV inverters)
- Switch mode power supplies (SMPS)
- Applications using the following topologies
 - LCC
 - Phase shifted bridge (ZVS)
 - 3-level inverter
 - AC/DC bridge

PRODUCT SUMMARY

V_{DS} (V) at T_J max.	700	
$R_{DS(on)}$ max. (Ω) at 25 °C	$V_{GS} = 10$ V	0.156
Q_g max. (nC)	122	
Q_{gs} (nC)	17	
Q_{gd} (nC)	36	
Configuration	Single	

ORDERING INFORMATION

Package	Thin-Lead TO-220 FULLPAK
Lead (Pb)-free	SiHA24N65EF-E3
Lead (Pb)-free and halogen-free	SiHA24N65EF-GE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)


PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-source voltage	V_{DS}	650	V	
Gate-source voltage	V_{GS}	± 30		
Continuous drain current ($T_J = 150$ °C) ^e	V_{GS} at 10 V	$T_C = 25$ °C	24	A
		$T_C = 100$ °C	15	
Pulsed drain current ^a	I_{DM}	65		
Linear derating factor		0.31	W/°C	
Single pulse avalanche energy ^b	E_{AS}	691	mJ	
Maximum power dissipation	P_D	39	W	
Operating junction and storage temperature range	T_J, T_{stg}	-55 to +150	°C	
Drain-source voltage slope	dV/dt	$T_J = 125$ °C	70	V/ns
Reverse diode dV/dt ^d		50		
Soldering recommendations (peak temperature) ^c	for 10 s	300	°C	
Mounting torque	M3 screw	0.6	Nm	

Notes

- Repetitive rating; pulse width limited by maximum junction temperature
- $V_{DD} = 50$ V, starting $T_J = 25$ °C, $L = 28.2$ mH, $R_g = 25$ Ω , $I_{AS} = 7$ A
- 1.6 mm from case
- $I_{SD} \leq I_D$, $dI/dt = 900$ A/ μ s, starting $T_J = 25$ °C
- Limited by maximum junction temperature



THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	65	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	3.2	

SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA		650	-	-	V
V _{DS} temperature coefficient	ΔV _{DS} /T _J	Reference to 25 °C, I _D = 1 mA		-	0.68	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		2	-	4	V
Gate-source leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
		V _{GS} = ± 30 V		-	-	± 1	μA
Zero gate voltage drain current	I _{DSS}	V _{DS} = 520 V, V _{GS} = 0 V		-	-	1	μA
		V _{DS} = 520 V, V _{GS} = 0 V, T _J = 125 °C		-	-	500	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 12 A	-	0.13	0.156	Ω
Forward transconductance	g _{fs}	V _{DS} = 30 V, I _D = 12 A		-	7.2	-	S
Dynamic							
Input capacitance	C _{iSS}	V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz		-	2774	-	pF
Output capacitance	C _{oss}			-	128	-	
Reverse transfer capacitance	C _{rSS}			-	4	-	
Effective output capacitance, energy related ^a	C _{o(er)}			-	96	-	
Effective output capacitance, time related ^b	C _{o(tr)}	V _{DS} = 0 V to 520 V, V _{GS} = 0 V		-	333	-	
Total gate charge	Q _g	V _{GS} = 10 V	I _D = 12 A, V _{DS} = 520 V	-	81	122	nC
Gate-source charge	Q _{gs}			-	17	-	
Gate-drain charge	Q _{gd}			-	36	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 520 V, I _D = 12 A, V _{GS} = 10 V, R _g = 9.1 Ω		-	24	48	ns
Rise time	t _r			-	34	68	
Turn-off delay time	t _{d(off)}			-	80	120	
Fall time	t _f			-	46	92	
Gate input resistance	R _g	f = 1 MHz, open drain		0.2	0.5	1.0	Ω
Drain-Source Body Diode Characteristics							
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	24	A
Pulsed diode forward current	I _{SM}			-	-	65	
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 12 A, V _{GS} = 0 V		-	0.9	1.2	V
Reverse recovery time	t _{rr}	T _J = 25 °C, I _F = I _S = 12 A, di/dt = 100 A/μs, V _R = 400 V		-	151	288	ns
Reverse recovery charge	Q _{rr}			-	0.9	2.1	μC
Reverse recovery current	I _{RRM}			-	13	-	A

Notes

- a. C_{oss(er)} is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}
- b. C_{oss(tr)} is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

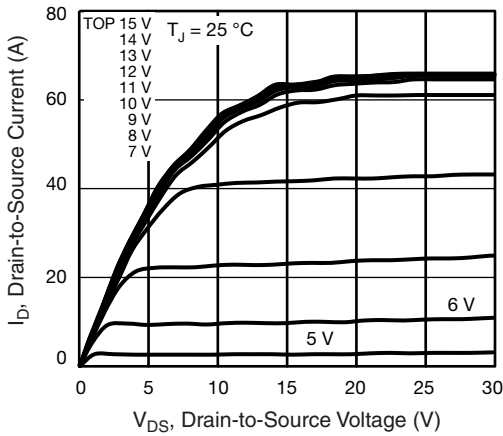


Fig. 1 - Typical Output Characteristics

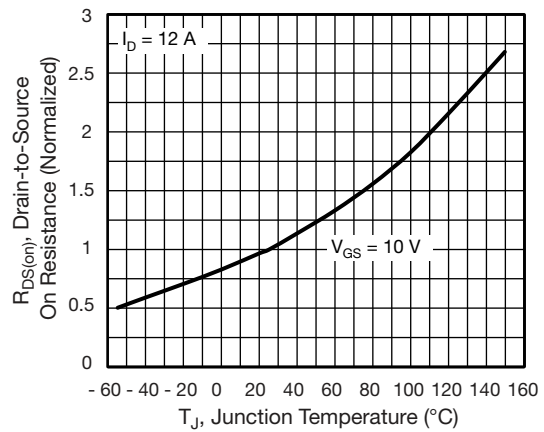


Fig. 4 - Normalized On-Resistance vs. Temperature

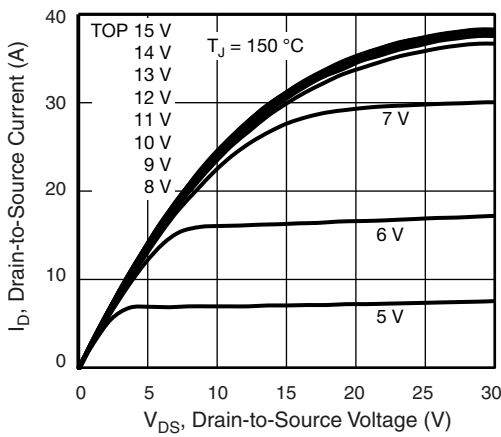


Fig. 2 - Typical Output Characteristics

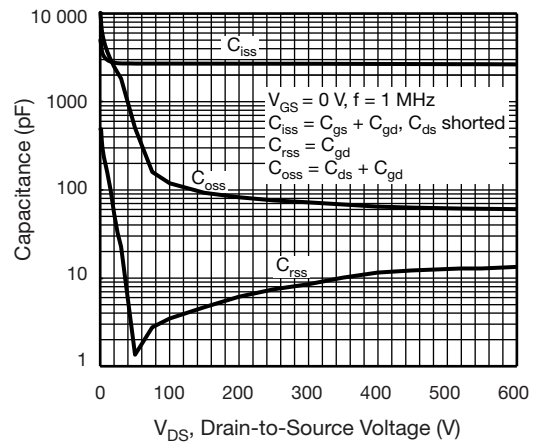


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

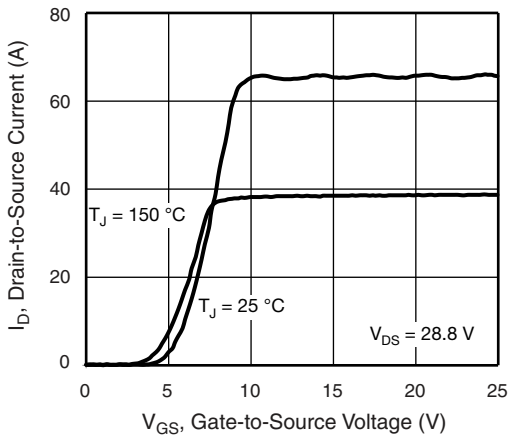


Fig. 3 - Typical Transfer Characteristics

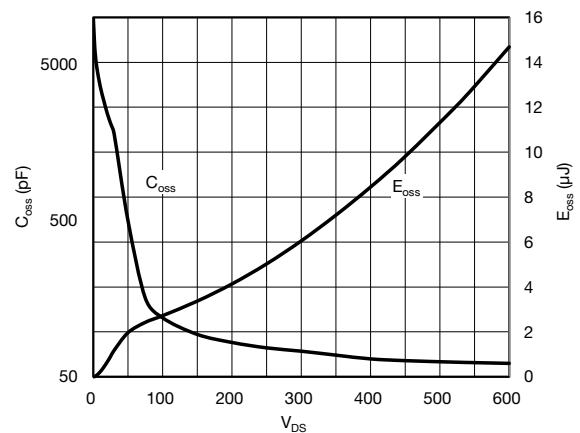


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}

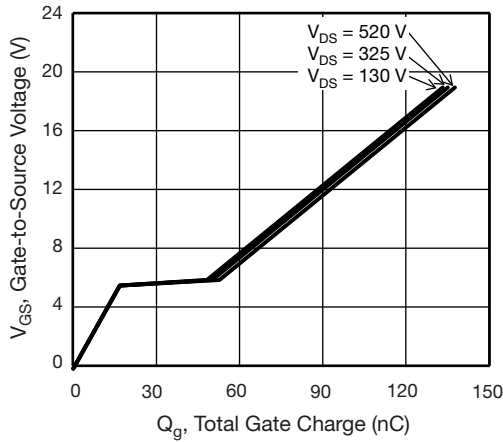


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

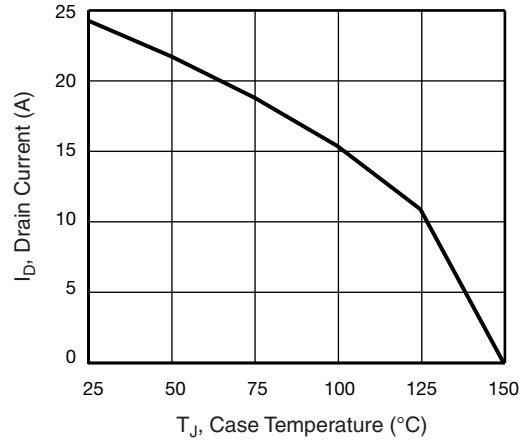


Fig. 10 - Maximum Drain Current vs. Case Temperature

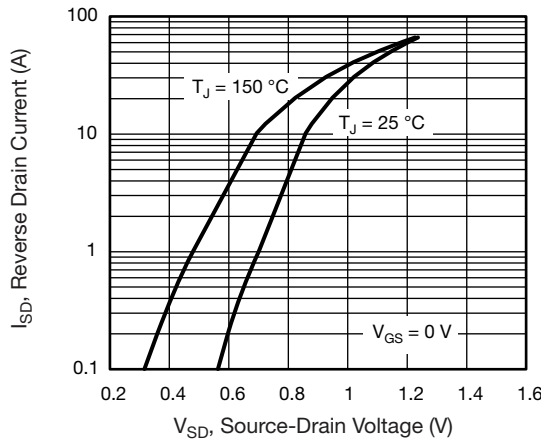


Fig. 8 - Typical Source-Drain Diode Forward Voltage

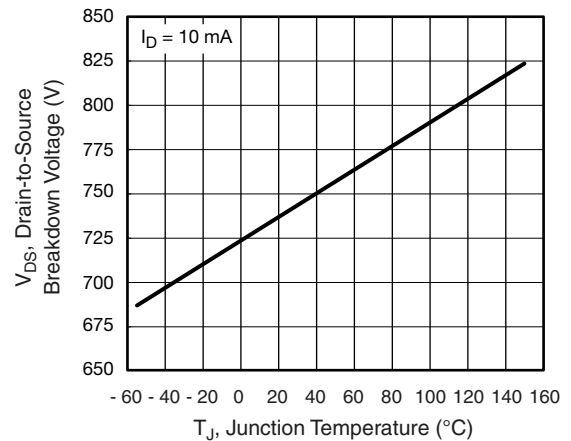


Fig. 11 - Temperature vs. Drain-to-Source Voltage

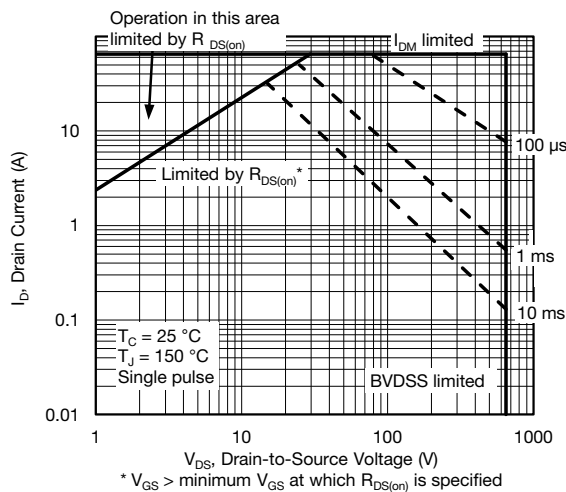


Fig. 9 - Maximum Safe Operating Area

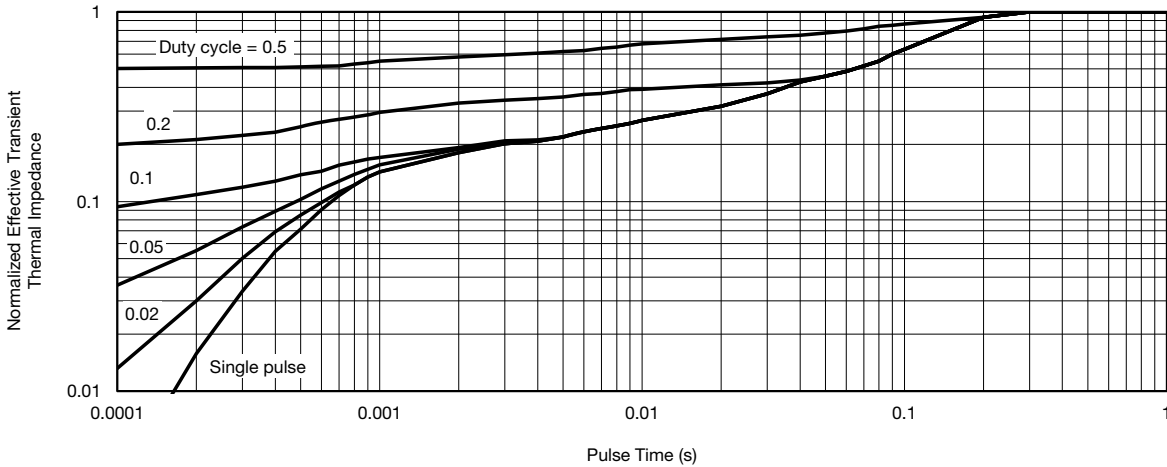


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

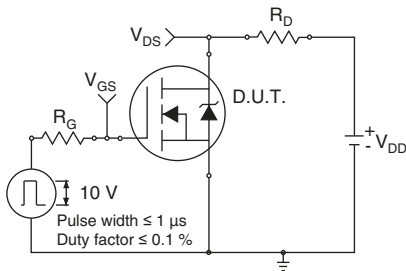


Fig. 13 - Switching Time Test Circuit

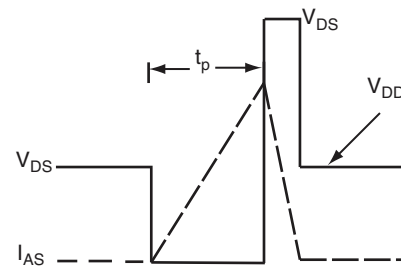


Fig. 16 - Unclamped Inductive Waveforms

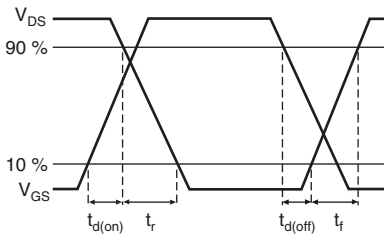


Fig. 14 - Switching Time Waveforms

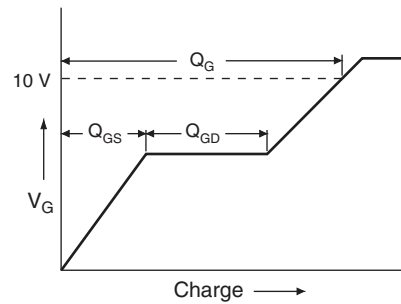


Fig. 17 - Basic Gate Charge Waveform

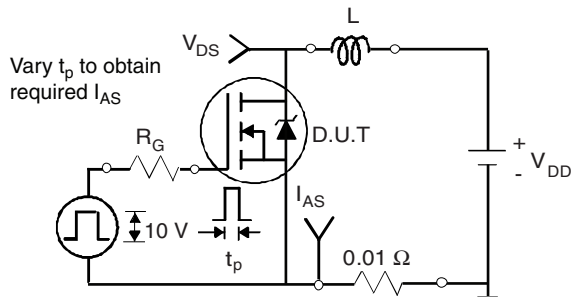


Fig. 15 - Unclamped Inductive Test Circuit

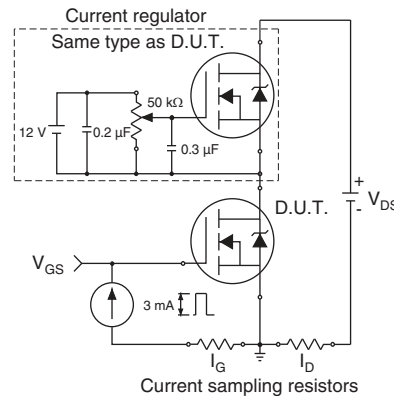


Fig. 18 - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



Note

a. $V_{GS} = 5 V$ for logic level devices

Fig. 19 - For N-Channel

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